



HoRF1206陶瓷合金系列规格书

系列号	HoRF
修订日期	2021-12-22
版本号	Ho-A0

规格书 Specification

制造商: 深圳市毫欧电子有限公司

HoRF1206

Scope

- This specification applies to all sizes of rectangular-type fixed chip resistors with Ruthenium-base as material.

Features

- Small size and light weight
- Highly reliable multilayer electrode construction
- Compatible with all soldering process
- Long side terminations

Applications

- Telecommunication Equipments
- Radio and Tape Recorders, TV Tuners
- Digital Cameras, Watches, Pocket Calculators
- Computers, Instruments
- Medical Equipment

Ho	RF	1206	1W	10mR	1%
↓	↓	↓	↓	↓	↓
制造商	产品类别	封装	额定功率	阻值	精度
毫欧电子	陶瓷合金	1206	1/4W	1Ω~100MΩ	D=±0.5% F=±1% J=±5% B: ±0.1% C: ±0.25%
			1/2W	1Ω~1MΩ	

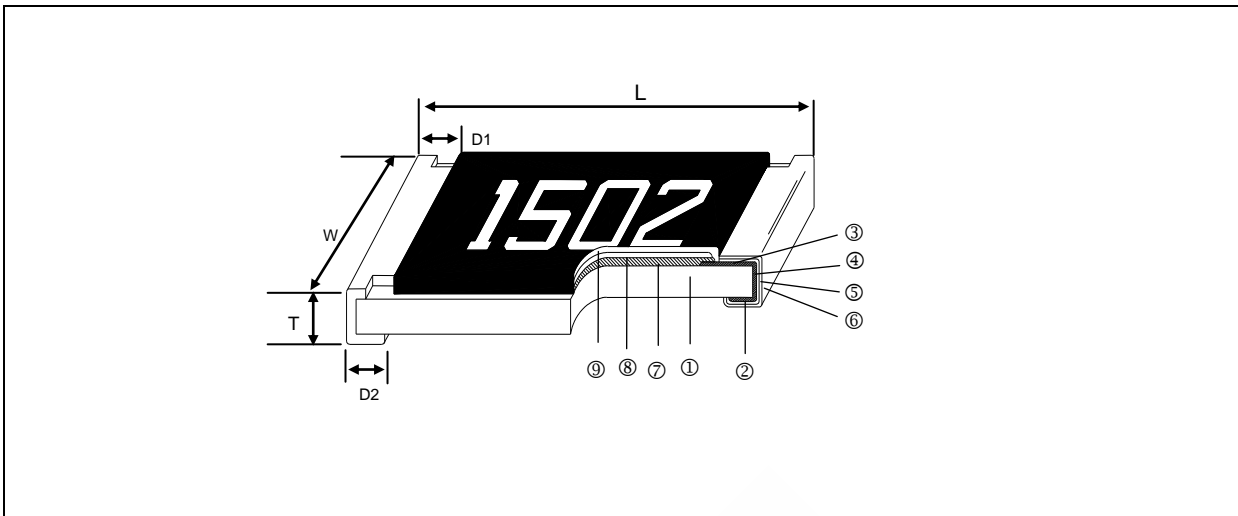
具体参数请查看下页详情



地址: 深圳市龙华新区观澜大布头路南通邦高新产业园 A栋 8 楼

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■ 产品结构及尺寸 **Product structure ansize** (Unit:mm)



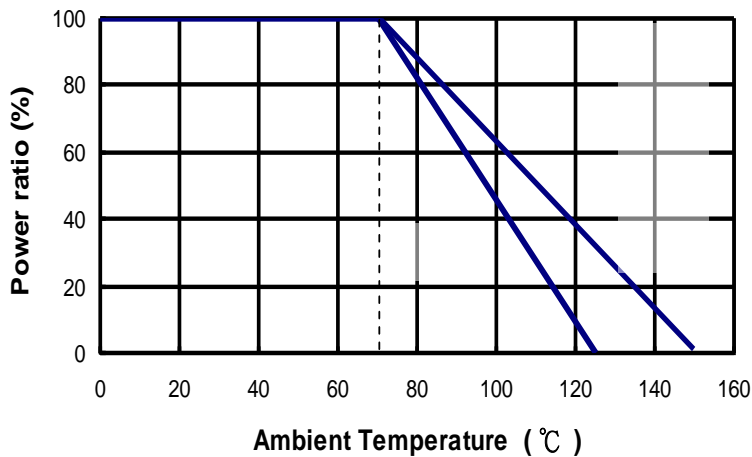
封装	L	W	T	D1	T
1206	3.1±0.1	1.55±0.1	0.55±0.1	0.5±0.25	0.5±0.20

■ 电气参数 **Electrical parameter**

额定功率 Rated power	1/4W、1/2W
阻值范围 Resistance range	1Ω~100MΩ, 1Ω~1MΩ
最大额定电流 Max.Rated Current	0.5A ,0.7
准确度等级 AccuracyClass	0.5%、1%、5%、0.1%、0.25%
电阻温度系数 T.C.R (ppm / °C)	≤±400
工作温度范围 Operating Temperature Range	-50°C~+170°C

■ 功率曲线 **Power curve**

操作温度范围 - 50 ~ +170 °C 电阻温度达到 70°C 时降功率 示意图



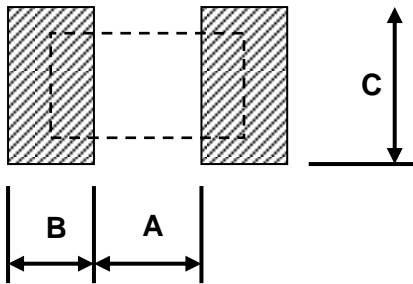
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■ 额定电流计算公式 The rated current is calculated by the following Formu

$$I = \sqrt{P/R}$$

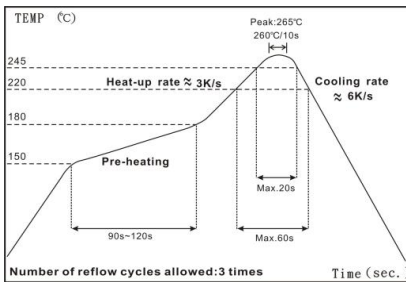
I :Rated Current (A)
P:Rated Power (W)
R:Resistance Value (Ω)

■ 建议焊盘尺寸 Recommended Solder Pad Dimension (Unit:mm)

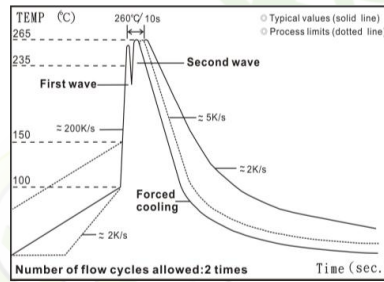


封装	A	B	C	
1206	2.0	0.9	1.6	

■ Soldering Condition



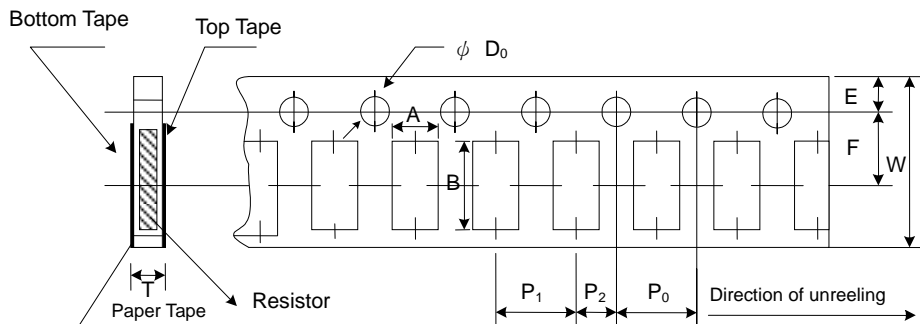
IR Reflow Soldering



Wave Soldering (Flow Soldering)

- (1) Time of IR reflow soldering at maximum temperature point 260°C : 10s
- (2) Time of wave soldering at maximum temperature point 260°C : 10s
- (3) Time of soldering iron at maximum temperature point 410°C : 5s

■ 彩带尺寸 Ribbon size (Unit:mm)



封装	A	B	W	F	E	P1	P2	P0	D0	T
1206	1.9±0.1	3.50±0.20	8±0.2	3.50±0.05	1.75±0.10	4.0±0.05	2±0.05	4±0.05	Φ 1.5+0.1	0.85±0.15

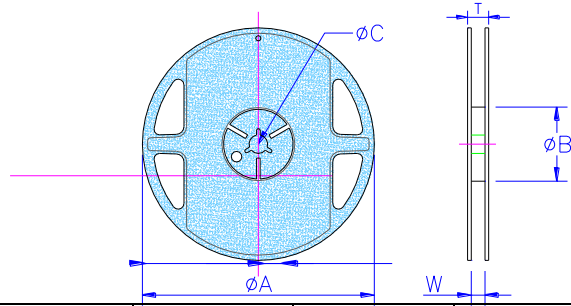
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■ 卷轴规格 Reel Specification (Unit:mm)



Type	Packaging Quantity	Tape Width	Reel Diameter	ΦA (mm)	ΦB (mm)	ΦC (mm)	W (mm)	T (mm)	
HoRF1206	Paper	5K	8mm	7 inch	178.5±1.5	60 ^{+1/-0}	13.0±0.2	9.0±0.5	12.5±0.5
		10K	8mm	10 inch	254±1.0	100±0.5	13.0±0.2	9.5±0.5	13.5±0.5
		20K	8mm	13 inch	330±1.0	100±0.5	13.0±0.2	9.5±0.5	13.5±0.5

■ 可靠性测试 Reliability Tests

Test Items	Reference standard	Condition of Test	Test Limits
Temperature Coefficient of Resistance	IEC60115-1-4.8 JIS-C5201-4.8	+25°C ~ +125°C	Refer 4.0
Load Life	IEC60115-1-4.25.1 JIS-C5201-4.25.1	1000hours at rated power, 70°C, 1.5hours "ON", 0.5hour "OFF"	< ±1%
Short Time Overload	IEC60115-1-4.13 JIS-C5201-4.13	2 X rated power for 5s	< ±1%
Moisture no Load	IEC60115-1- 4.24.2.1a) JIS-C5201- 4.24.2.1a)	85°C, 85%RH, 1000hrs	< ±1%
Temperature cycle	IEC60115-1-4.19 JIS-C5201-4.19	-55°C & +155°C, 100cycle, 15min per extreme condition	< ±1%
Resistance to Soldering Heat	IEC60115-1-4.18 JIS-C5201-4.18	260±5°C for 10±1 sec	< ±0.5%
Solderability	IEC60115-1-4.17 JIS-C5201-4.17	245±5°C, 2±0.5sec	At least 95% of surface area of electrode shall be covered with new solder
High Temperature Exposure	IEC60115-1- 4.23.2 JIS-C5201-4.23.2	155°C, 1000hrs	< ±1%
Low Temperature Storage	IEC60115-1- 4.23.4 JIS-C5201-4.23.4	-55°C, 1000hrs	< ±1%
Substrate Bending	IEC60115-1-4.33 JIS-C5201-4.33	Bending width 2mm	< ±0.5%
Insulation Resistance	IEC60115-1-4.6 JIS-C5201-4.6	100V DC for 1 minute	>100 MΩ

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